



Designation: D3808 – 01 (Reapproved 2013)

Standard Test Method for Qualitative Determination of Adhesion of Adhesives to Substrates by Spot Adhesion¹

This standard is issued under the fixed designation D3808; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ϵ) indicates an editorial change since the last revision or reapproval.

1. Scope

1.1 This test method covers a simple qualitative procedure for quickly screening whether an adhesive will, under recommended application conditions, bond to a given substrate without actually making bonded assemblies.

1.2 The values stated in SI units are to be regarded as the standard. The values in parentheses are for information only.

1.3 *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.*

2. Referenced Documents

2.1 *ASTM Standards:*²

D907 Terminology of Adhesives

E171 Practice for Conditioning and Testing Flexible Barrier Packaging

3. Terminology

3.1 *Definitions*—Many of the terms used in this test method are defined in Terminology D907.

3.1.1 *spot adhesion, n*—a qualitative method of determining adhesion by attempting to pry a “spot” of cured adhesive from a substrate.

4. Summary of Test Method

4.1 Spots of adhesive (size can vary, but generally about 6 mm (1/4 in.) in diameter) are placed onto a substrate using the application procedure and curing conditions acceptable to both user and supplier of the adhesive.

¹ This test method is under the jurisdiction of ASTM Committee D14 on Adhesives and is the direct responsibility of Subcommittee D14.40 on Adhesives for Plastics.

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² For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For *Annual Book of ASTM Standards* volume information, refer to the standard's Document Summary page on the ASTM website.

4.2 The substrate preparation and environmental exposure of the spot of adhesive after cure or setting can be varied as desired.

4.3 The determination of whether an adhesive bonds to the substrate is made by simply trying to pry the spot of adhesive from the substrate.

4.4 The mode of failure is readily evident by examining whether the bond separated adhesively or cohesively, either in the adhesive or substrate.

5. Significance and Use

5.1 This is a quick, simple, and inexpensive test method for qualitatively determining, without the need to prepare bonded test specimens, whether the adhesive under consideration will bond to a particular substrate. If the results are acceptable, then standard quantitative adhesive test procedures can be used to obtain quantitative measurements of the adhesive's performance.

5.2 This test method can also be used to compare relative adhesion of several adhesives to given substrates.

5.3 It can be used to determine whether an adhesive will continue to adhere to the substrate under specified environmental conditions.

5.4 It can be used to evaluate adhesion of a particular adhesive to a variety of substrates.

5.5 It can be used to obtain “subjective” comparative data between several adhesives on a given substrate by noting the relative ease of inducing failure between the adhesives tested.

5.6 It should be most applicable to adhesives that cure or set when exposed to “air” (ambient, heated, etc.) and could be used for anaerobic adhesives if testing is carried out in an oxygen-free atmosphere.

6. Apparatus

6.1 No special equipment is needed for application of the adhesive to the test substrate(s). When using hot-melt adhesives, for example, it would be desirable to have a hand-gun applicator or equivalent apparatus to allow deposition of the hot-melt at a recommended application temperature. The use of such equipment is not mandatory as a hot plate can